

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE



**Field device integration (FDI) –  
Part 103-4: Profiles – PROFINET**

**Intégration des appareils de terrain (FDI) –  
Partie 103-4: Profils – PROFINET**



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INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

COMMISSION  
ELECTROTECHNIQUE  
INTERNATIONALE

ICS 25.040.40; 35.100

ISBN 978-2-8322-2624-7

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## FIELD DEVICE INTEGRATION (FDI) –

## Part 103-4: Profiles – PROFINET

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The text of this standard is based on the following documents:

CDV	Report on voting
65E/355/CDV	65E/418/RVC

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

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## FIELD DEVICE INTEGRATION (FDI) –

### Part 103-4: Profiles – PROFINET

#### 1 Scope

This part of IEC 62769 specifies an FDI profile of IEC 62769 for IEC 61784-2\_CP 3/4, IEC 61784-2\_CP3/5 and IEC 61784-2\_CP3/6 (PROFINET<sup>1</sup>).

#### 2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61158-5-10, *Industrial communication networks – Fieldbus specifications – Part 5-10: Application layer service definition – Type 10 elements*

IEC 61784-2, *Industrial communication networks – Profiles – Part 2: Additional fieldbus profiles for real-time networks based on ISO/IEC 8802-3*

IEC 61804 (all parts), *Function blocks (FB) for process control and Electronic Device Description Language (EDDL)*

IEC 62541-100:2015, *OPC Unified Architecture – Part 100: OPC UA for Devices*

IEC 62769-2, *Field Device Integration (FDI) – Part 2: FDI Client*

NOTE 1 IEC 62769-2 is technically identical to FDI-2022.

IEC 62769-4, *Field Device Integration (FDI) – Part 4: FDI Packages*

NOTE 2 IEC 62769-4 is technically identical to FDI-2024.

IEC 62769-5, *Field Device Integration (FDI) – Part 5: FDI Information Model*

NOTE 3 IEC 62769-5 is technically identical to FDI-2025.

IEC 62769-6, *Field Device Integration (FDI) – Part 6: FDI Technology Mapping*

NOTE 4 IEC 62769-6 is technically identical to FDI-2026.

IEC 62769-7, *Field Device Integration (FDI) – Part 7: FDI Communication Devices*

NOTE 5 IEC 62769-7 is technically identical to FDI-2027.

PI Order No.: 2.122:2008, *Specification for PROFIBUS – Device Description and Device Integration – Volume 1: GSD, V5.1, July 2008: GSD*; available at <[www.PROFIBUS.com](http://www.PROFIBUS.com)>

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